MA22F200G

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Super high speed switching characteristic (t_{rr} = 8 ns typ.)
- At the same time as lowering the wiring inductance and increasing the peak surge forward current, the resistance to surge damage at power on has been increased by adopting clip connection package (TMP).

■ Package

- Code
  Mini2-F2
- Pin Name
  1: Anode
  2: Cathode

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	200	V
Non-repetitive peak reverse surge voltage	V_{RSM}	200	V
Forward current *1	I_F	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	15	A
Junction temperature	T_j	–40 to +150	°C
Storage temperature	T_{stg}	–40 to +150	°C

Note) *1: Mounted on an alumina PC board
*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

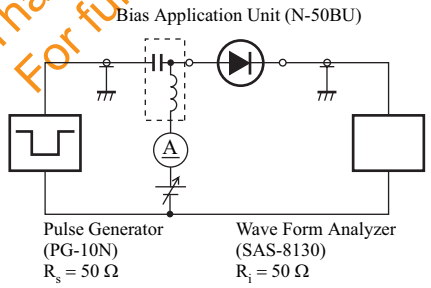
■ Marking Symbol: FB

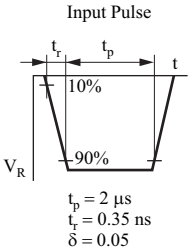
■ Internal Connection

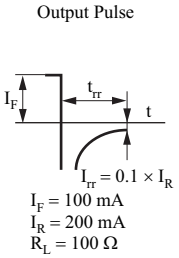
■ Electrical Characteristics T_a = 25°C±3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 1.0 A		0.85	0.98	V
Reverse current	I_{RRM}	V_{RRM} = 200 V			20	μA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		45		pF
Reverse recovery time *	t_{rr}	I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A		8	35	ns

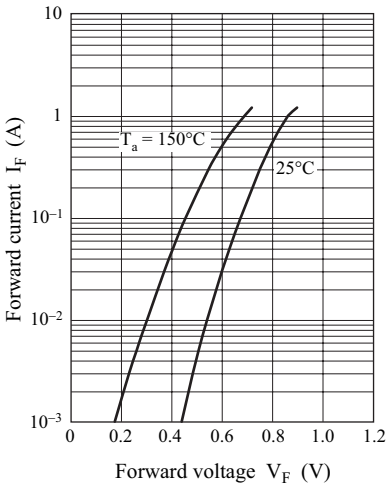
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. *: t_{rr} measurement circuit



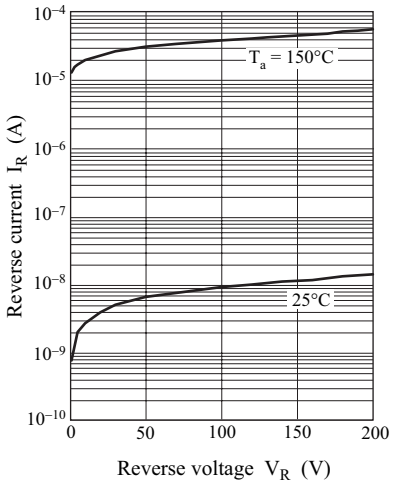




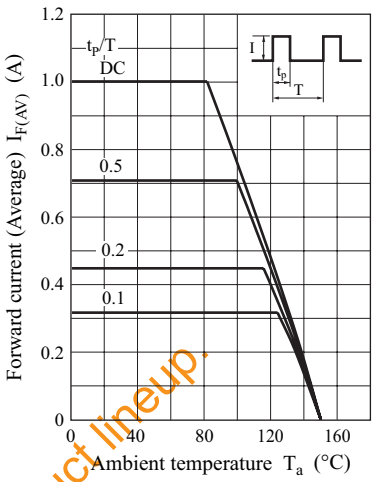
I_F — V_F



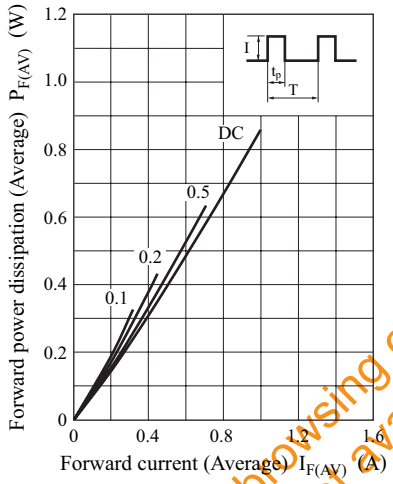
I_R — V_R



$I_{F(AV)}$ — T_a

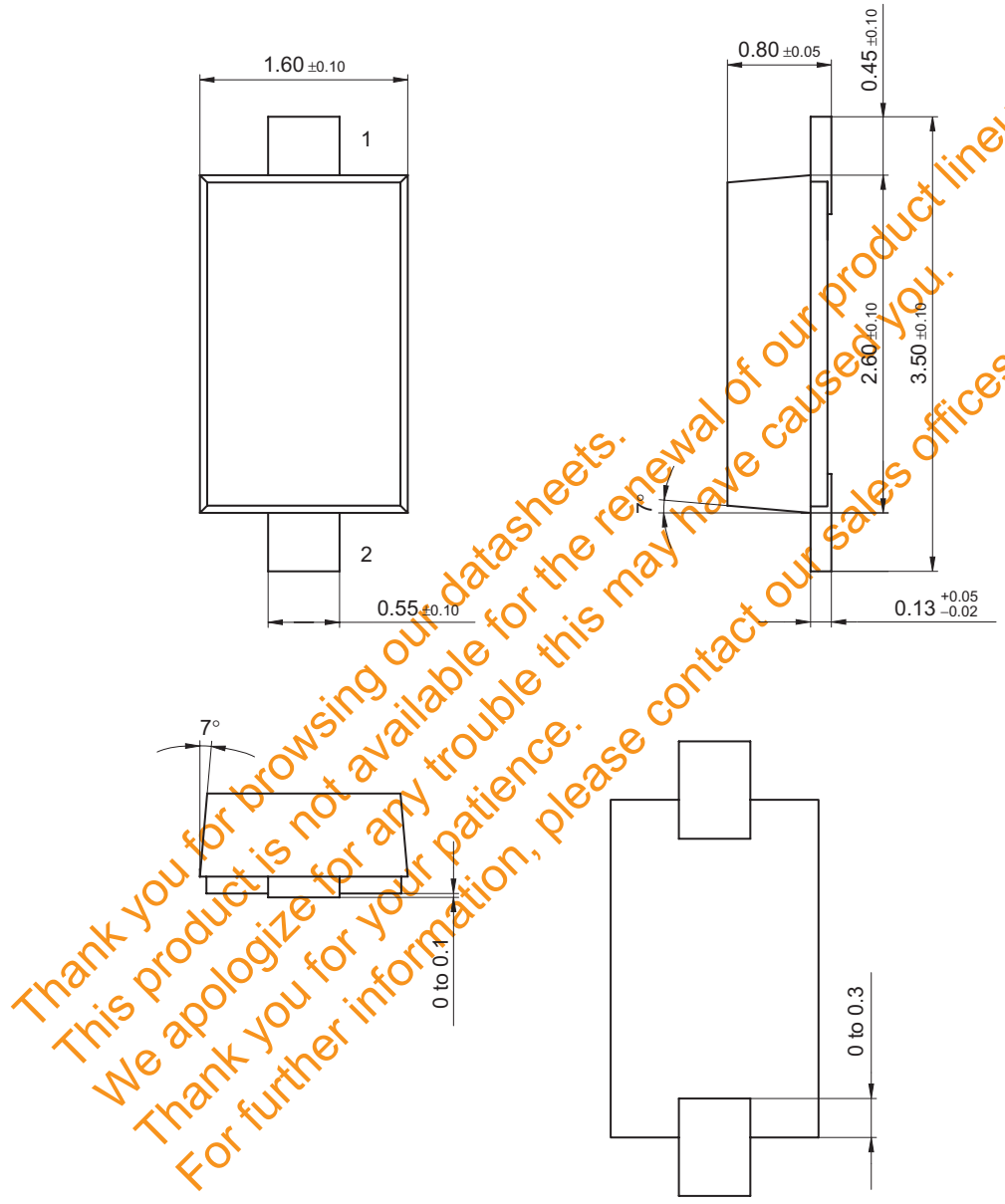


$P_{F(AV)}$ — $I_{F(AV)}$



Mini2-F2

Unit: mm



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